SPECIFICATION

SPEC NO. :

PART NO. :

PRODUCT NAME : **J 3570A**

DESCRIPTION : **Halogen Free RoHS Product**

REVISION STATUS

VERSION	DATE	PAGE	REVISION DESCRIPTION	PREPARED	CHECKED	APPROVED
d01	2023.03.27	All	New	曾靳毅	沈廷宜	陳勁豪

Prepared By	Checked By	Approved By

CIROCOMM TECHNOLOGY CORP.

PART NUMBER:

ELECTRICAL CHARACTERISTICS:

This filter satisfies Table 1 at Temperature Range : -40 to +100℃

CENTER FREQUENCY : fc =3570 MHz

PASSBAND WIDTH : 3470~3670 MHz

INPUT/OUTPUT IMPEDANCE :50Ω

Max. INPUT POWER : 1 W

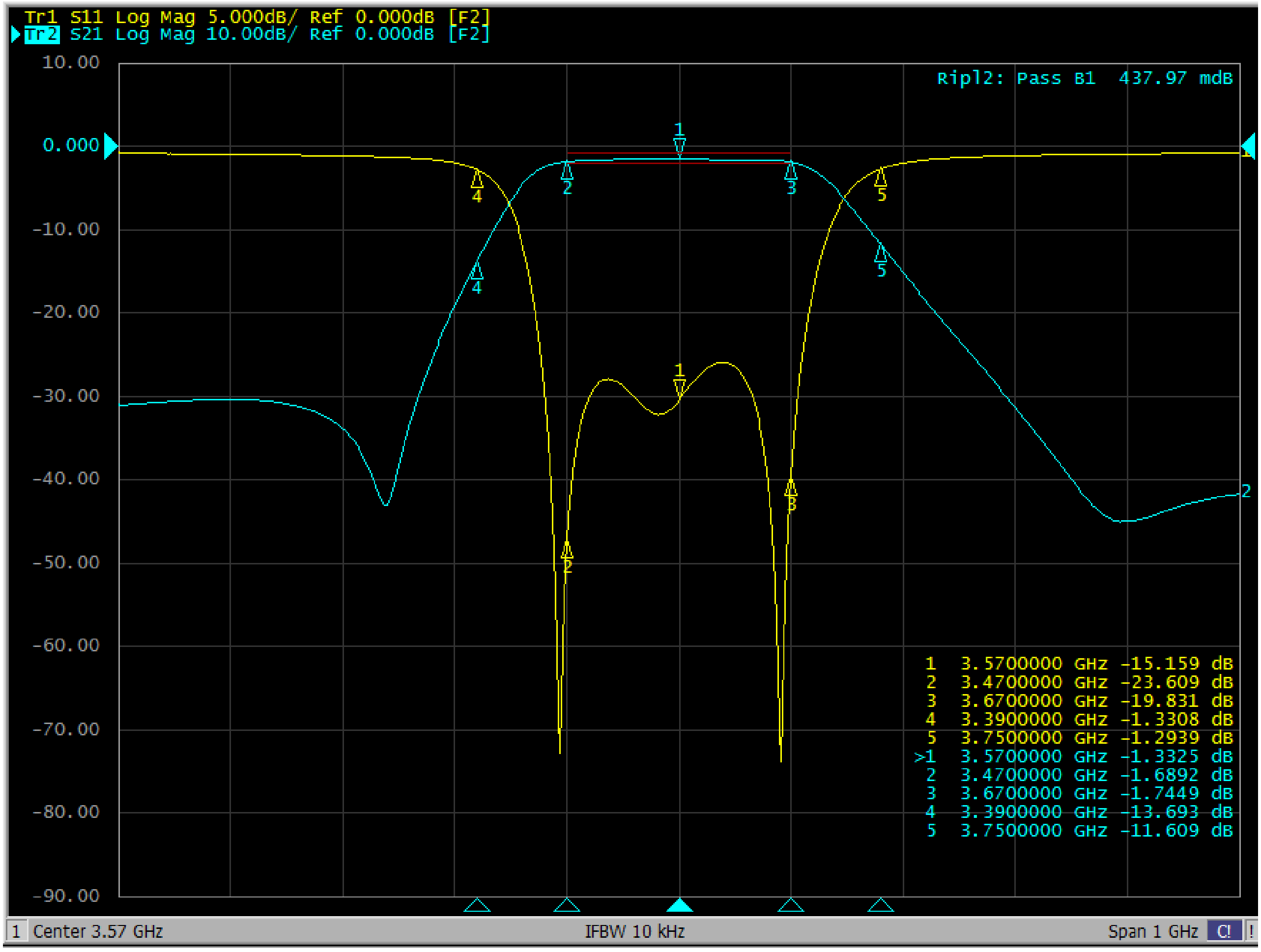
Moisture Sensitivity Level (MSL): 2a

TABLE 1

NO.	ITEM		SPECIFICATION		
			Min	Typ.	Max
1	PASS BAND INSERTION LOSS			2.0 dB	2.5 dB
2	PASS BAND RIPPLE			1.2 dB	1.5 dB
3	PASS BAND RETURN LOSS		10 dB	12 dB	
4	STOP—BAND ATTENUATION	at 3390 MHz	8 dB	10 dB	
		at 3750 MHz	8 dB	10 dB	
Item NO.4 specifies the absolute value of attenuation.					

※Data is measured on Cirocomm EVB board

TYPICAL ELECTRICAL CHARACTERISTICS



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  1  3.5700000 GHz -15.159 dB
  2  3.4700000 GHz -23.609 dB
  3  3.6700000 GHz -19.831 dB
  4  3.3900000 GHz -1.3308 dB
  5  3.7500000 GHz -1.2939 dB
 >1  3.5700000 GHz -1.3325 dB
  2  3.4700000 GHz -1.6892 dB
  3  3.6700000 GHz -1.7449 dB
  4  3.3900000 GHz -13.693 dB
  5  3.7500000 GHz -11.609 dB
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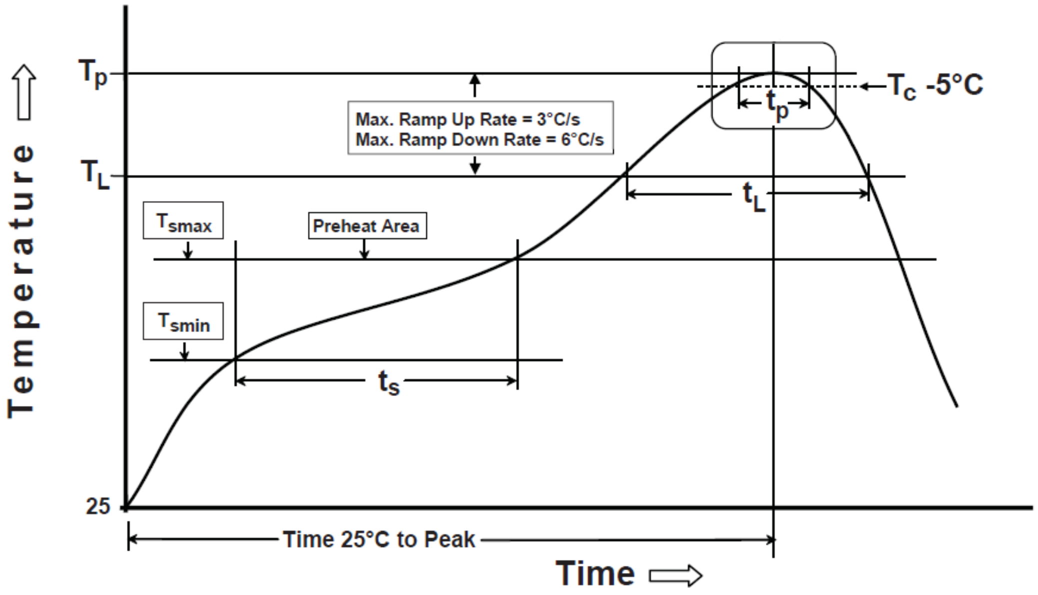
2. Recommended Reflow Soldering Profile

Cirocomm products can be assembled following Pb-free assembly. According to the Standard **IPC/JEDEC J-STD-020C**, the temperature profile suggested is as follow:

Phase	Profile features	Pb-Free Assembly (SnAgCu)
PREHEAT	-Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(ts) form (Tsmin to Tsmax)	150℃ 200℃ 60-120 seconds
RAMP-UP	Avg. Ramp-up Rate (Tsmax to TP)	3℃/second(max)
REFLOW	-Temperature(TL) -Total Time above TL (t L)	217℃ 30-100 seconds
PEAK	-Temperature(TP) -Time(tp)	260℃ 3 second
RAMP-DOWN	Rate	6℃ / second max.
Time from 25℃ to Peak Temperature		8 minutes max.
Composition of solder paste		96.5Sn/3Ag/0.5Cu
Solder Paste Model		SHENMAO PF606-P26

Note：All the temperature measure point is on top surface of the component, if temperature over recommend, it will make component surface peeling or damage.

The graphic shows temperature profile for component assembly process in reflow ovens



Soldering With Iron:

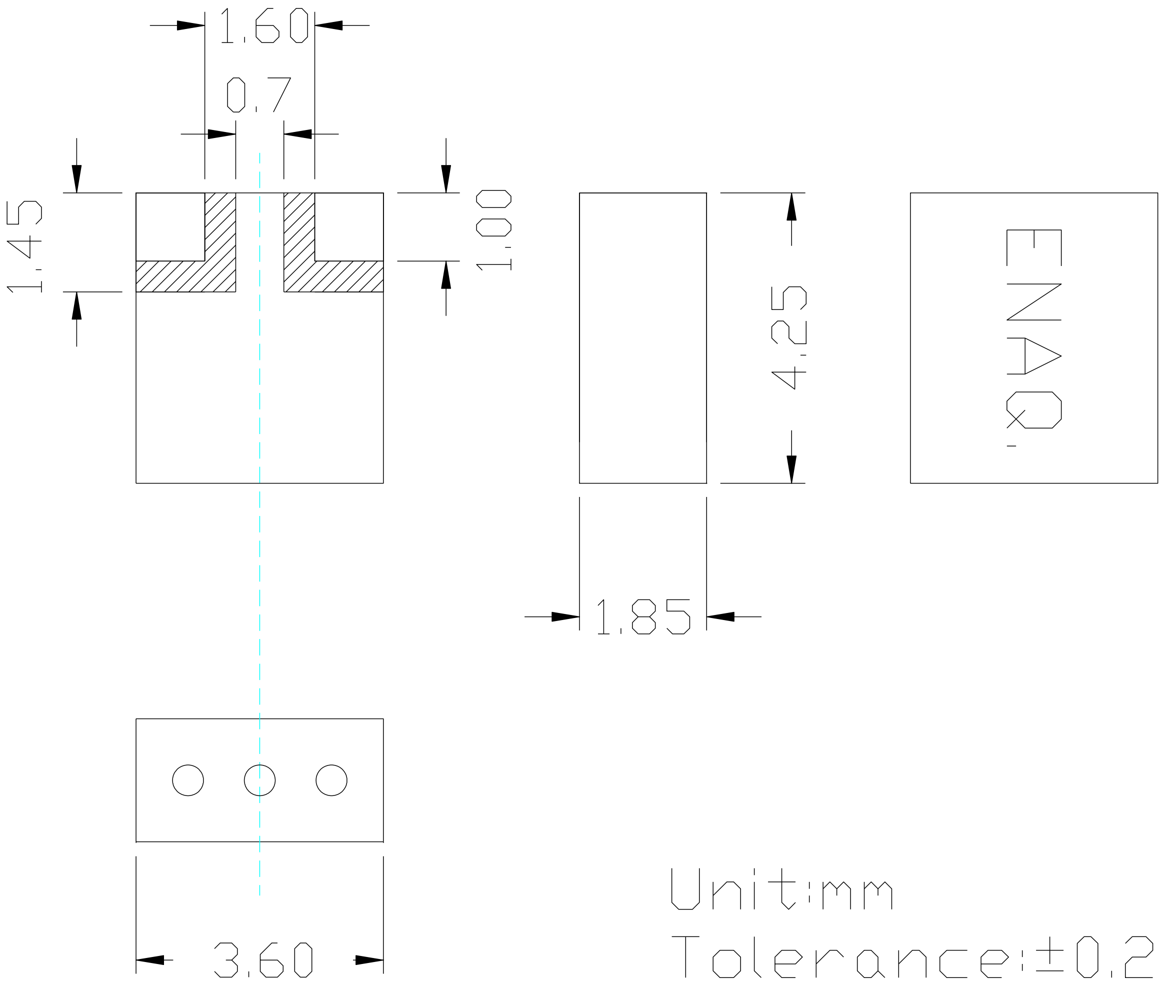
Soldering condition : Soldering iron temperature 270±10 ℃.

Apply preheating at 120℃ for 2-3 minutes. Finish soldering for each terminal within 3 seconds, if soldering iron over temperature 270±10 ℃ or 3 seconds, it will make component surface peeling or damage.

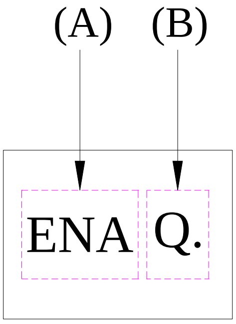
Soldering iron cannot leakage of electricity.

3. DIMENSION AND PCB LAYOUT

3-1 SHAPE AND DIMENSION



3-1-2 MARKING



(A) Product name : ENA for 3570A
(B) Year/Month : Please refer to the Table-2

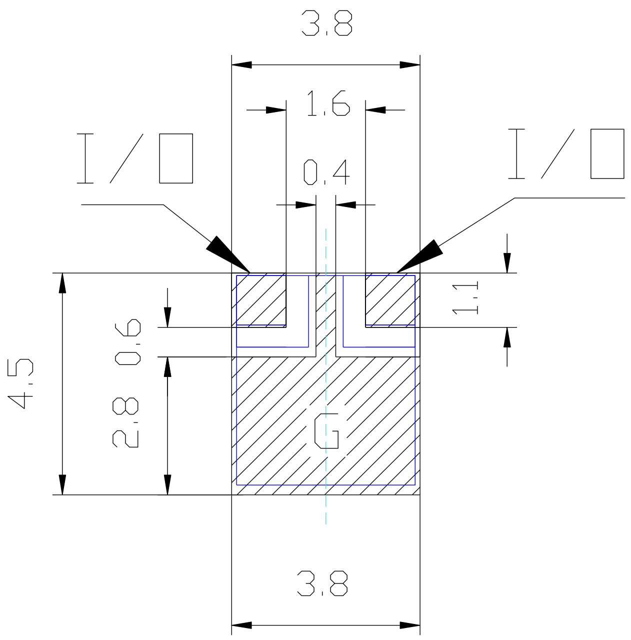
(Table-2)

Year	Month	Code	Year	Month	Code	Year	Month	Code	Year	Month	Code
2012 2016 2020 2024	1	A	2013 2017 2021 2025	1	N	2014 2018 2022 2026	1	A .	2015 2019 2023 2027	1	N .
	2	B		2	P		2	B .		2	P .
	3	C		3	Q		3	C .		3	Q .
	4	D		4	R		4	D .		4	R .
	5	E		5	S		5	E .		5	S .
	6	F		6	T		6	F .		6	T .
	7	G		7	U		7	G .		7	U .
	8	H		8	V		8	H .		8	V .
	9	J		9	W		9	J .		9	W .
	10	K		10	X		10	K .		10	X .
	11	L		11	Y		11	L .		11	Y .
	12	M		12	Z		12	M .		12	Z .

3-2 PCB RECOMMENDED PATTERN FOR FILTER

Note: Test PCB material: ROGERS (RO4003C), 0.5mm.

The filter use limit: the layout goes away PCB edge.



☐ Filter Outline

▨ I/O Pads must be connected to lines with 50Ω impedance. In the applicationa termination of 50Ω must be realized.